

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L9 | 277 | (bond\$5 with pillar with (chip wafer die)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/17 07:32 |
| L10 | 117 | (bond\$5 with pillar with (chip wafer die) with pad) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/17 07:32 |
| L11 | 8 | 10 and vlsi | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/17 07:34 |
| L12 | 164 | 9 and ("385"/\$.ccls. "257"/\$.ccls.) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/17 07:35 |
| L13 | 78 | 10 and ("385"/\$.ccls. "257"/\$.ccls.) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/17 07:35 |
| L14 | 70 | 13 not 11 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/17 07:36 |

EAST Search History

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|-----|-----|---|---|----|-----|------------------|
| L15 | 47 | ("20020171177" "20030102566" "20030111727" "20030151167" "3777221" "5014161" "5291061" "5302778" "5435734" "5477082" "5477086" "5532519" "5535101" "5558271" "5559444" "5561328" "5719436" "5767580" "5773320" "5777345" "5790839" "5793101" "5883814" "5900676" "5914535" "5973924" "5977640" "6064120" "6100593" "6150724" "6222246" "6232667" "6238949" "6239366" "6251488" "6259962" "6268584" "6310403" "6317333" "6376915" "6391251" "6392309" "6403882" "6524346" "6549821" "RE35119" "RE36613").PN. OR ("6984544"). URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2006/04/17 07:53 |
| L16 | 2 | ("20050053319").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/04/17 08:01 |
| S1 | 8 | 385/14.ccls. and \$5damascene | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:09 |
| S2 | 183 | 385/14.ccls. and ((chip wafer substrate) with bond\$5 with pad) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/17 07:35 |
| S3 | 183 | 385/14.ccls. and ((chip wafer substrate) with bond\$5 with pad with (chip wafer substrate)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:32 |
| S4 | 19 | S3 and vlsi | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:12 |

EAST Search History

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|-----|------|--|---|----|----|------------------|
| S5 | 4 | 385/14.ccls. and (bond\$5 with pillar) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:34 |
| S6 | 10 | 385/14.ccls. and (bond\$5 with post) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:34 |
| S7 | 8 | S6 not S5 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:34 |
| S8 | 75 | 385/14.ccls. and (bond\$5 with (post pin)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:35 |
| S9 | 0 | S7 not (S4 S6 S1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:34 |
| S10 | 61 | S8 not (S4 S6 S1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:45 |
| S11 | 17 | 385/14.ccls. and (bond\$5 with (post pin) with pad) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:44 |
| S12 | 3403 | (bond\$5 with (post pin pillar) with pad) with (chip wafer substrate die ic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:45 |
| S13 | 31 | S12 and "385"/\$.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:57 |
| S14 | 23 | S13 not (S11 S4 S6 S1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 15:31 |

EAST Search History

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|-----|------|--|---|----|----|------------------|
| S15 | 269 | S12 and (waveguide fiber fibre light\$2guide) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:58 |
| S16 | 104 | S12 and ((waveguide fiber fibre light\$2guide) with (chip wafer substrate die ic)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 14:58 |
| S17 | 80 | S16 not (S14 S11 S4 S6 S1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 15:30 |
| S18 | 5858 | (pillar via) with bond\$5 with pad with (substrate chip wafer die) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 15:30 |
| S19 | 48 | (pillar via) with bond\$5 with pad with (substrate chip wafer die) with optic\$5 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 15:30 |
| S20 | 46 | S19 not (S17 S11 S4 S6 S1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 15:55 |

EAST Search History

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|-----|-----|--|---|----|-----|------------------|
| S21 | 179 | ("20020011663" "20020019305" "20020028045" "20020028537" "20020031297" "20020039464" "20030001240" "20030092243" "4422088" "4703993" "4711997" "4720634" "4732446" "4762382" "4774630" "4818045" "4838630" "4871224" "4912545" "4917450" "4933561" "4946253" "4966430" "5061027" "5100220" "5101460" "5130531" "5159700" "5163113" "5179609" "5198684" "5200631" "5237434" "5247597" "5330918" "5335361" "5337398" "5353498" "5420954" "5428704" "5446814" "5468681" "5499312" "5513021" "5533151" "5535296" "5631988" "5661831" "5675889" "5687267" "5692083" "5695933" "5790730" "5807783" "5812717" "5818107" "5854866" "5857049" "5900674" "5932387" "6046410" "6171887" "6236774" "6282352" "6293688" "6448168" "6517995").PN. OR ("5237434" "5638469" "6525407" "6741778" "6911392" "6935792").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2006/04/15 15:55 |
| S22 | 173 | S21 not (S20 S17 S11 S4 S6 S1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 15:56 |
| S23 | 56 | S22 and (bond\$5 with (pad pillar post)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 15:56 |
| S24 | 47 | S23 and optic\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/15 15:56 |